



SOT222-1

plastic dual in-line package; 24 leads (300 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP24
Package type industry code	DIP24
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-001
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

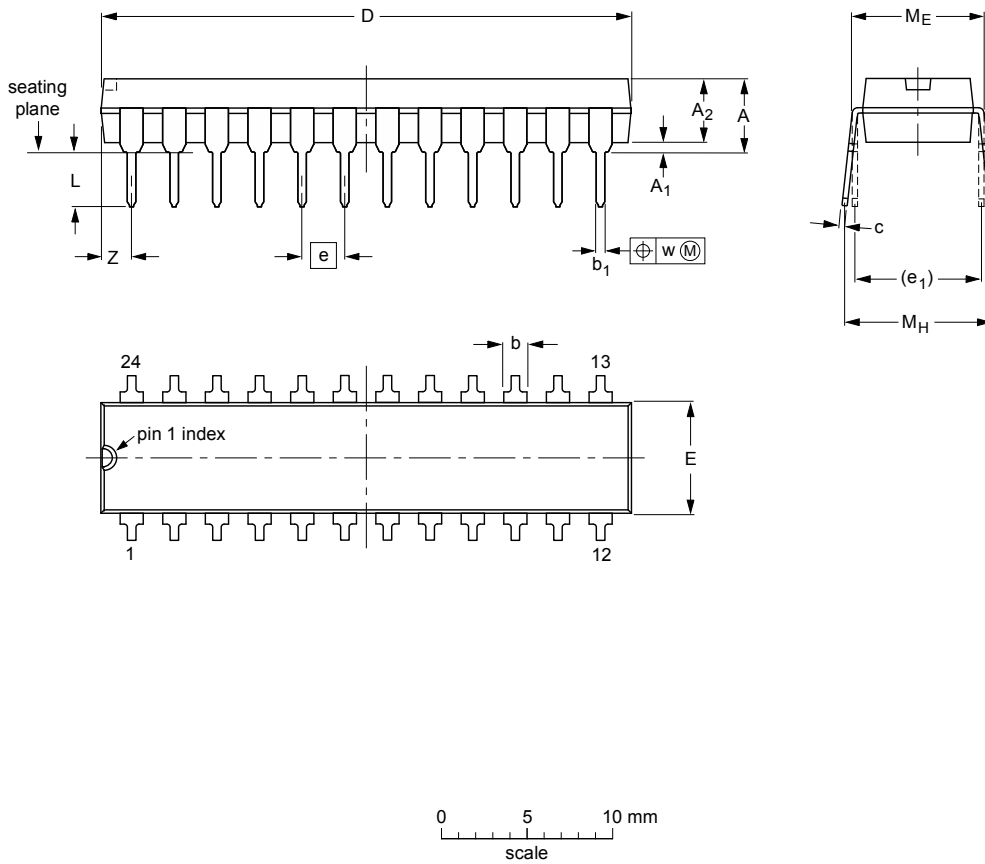
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	31.5	-	31.7	31.9	mm
E	package width	6.25	-	6.49	6.73	mm
A	seated height	[tbd]	-	4.7	4.7	mm
A ₂	package height	[tbd]	-	3.94	3.94	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

DIP24: plastic dual in-line package; 24 leads (300 mil)

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DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.25	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.246	0.1	0.3	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT222-1		MS-001				99-12-27 03-03-12

Fig. 1. Package outline DIP24 (SOT222-1)

3. Legal information

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